

**METHODS AND APPARATUS FOR CLEANING**  
**AN IC ENCAPSULATION SYSTEM**

5    **Abstract**

A system is proposed for encapsulating in plastics material leadframe items comprising an IC wired to a leadframe. Dust of the plastics material is removed from the encapsulation system, and in particular from those items  
10    where dust principally accumulates, such as the surfaces of the moulds. To reduce the level of dust which enters the moulding region, the path along which the leadframe items are conveyed to the moulding region is closed at times when the leadframe items are not being transported there. Additionally, the leadframe items are conveyed to the moulding region under a cover  
15    including a vacuum source, so that the dust is continually sucked away from them.